

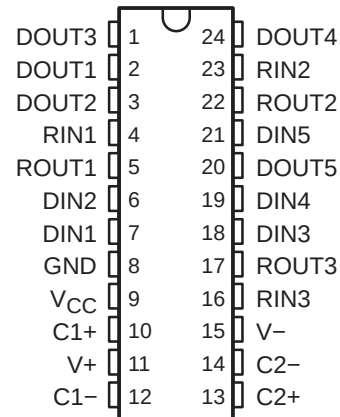
MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

- ESD Protection for RS-232 I/O Pins
 - ± 15 kV – Human-Body Model
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates at 5-V V_{CC} Supply
- Operates Up To 120 kbit/s
- External Capacitors . . . $4 \times 0.1 \mu\text{F}$
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment

DB OR DW PACKAGE
(TOP VIEW)



description/ordering information

The MAX207 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 5-V supply. The devices operate at data signaling rates up to 120 kbit/s and a maximum of 30-V/ μs driver output slew rate.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (DW)	Tube of 25	MAX207CDW	MAX207C
		Reel of 2000	MAX207CDWR	
	SSOP (DB)	Reel of 2000	MAX207CDBR	MA207C
–40°C to 85°C	SOIC (DW)	Tube of 25	MAX207IDW	MAX207I
		Reel of 2000	MAX207IDWR	
	SSOP (DB)	Reel of 2000	MAX207IDBR	MB207I

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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Function Tables

EACH DRIVER

INPUT D _{IN}	OUTPUT D _{OUT}
L	H
H	L

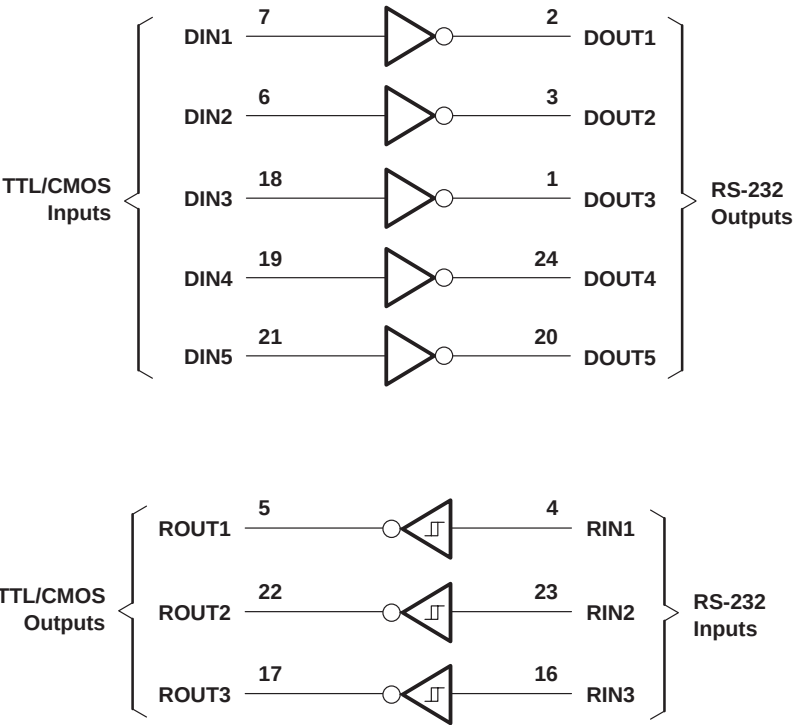
H = high level, L = low level

EACH RECEIVER

INPUT R _{IN}	OUTPUT R _{OUT}
L	H
H	L
Open	H

H = high level, L = low level, Open = input disconnected or connected driver off

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 6 V
Positive charge pump voltage range, $V+$ (see Note 1)	$V_{CC} - 0.3$ V to 14 V
Negative charge pump voltage range, $V-$ (see Note 1)	–14 V to 0.3 V
Input voltage range, V_I : Drivers	–0.3 V to $V+ + 0.3$ V
Receivers	± 30 V
Output voltage range, V_O : Drivers	$V- - 0.3$ V to $V+ + 0.3$ V
Receivers	–0.3 V to $V_{CC} + 0.3$ V
Short-circuit duration: D_{OUT}	Continuous
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	63°C/W
DW package	46°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 4)

			MIN	NOM	MAX	UNIT
	Supply voltage		4.5	5	5.5	V
V_{IH}	Driver high-level input voltage	D_{IN}	2			V
V_{IL}	Driver low-level input voltage	D_{IN}			0.8	V
V_I	Driver input voltage	D_{IN}	0		5.5	V
	Receiver input voltage		–30		30	
T_A	Operating free-air temperature	MAX207C	0		70	°C
		MAX207I	–40		85	

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 5$ V $\pm$ 0.5 V.

electrical characteristics over recommended ranges of supply voltage (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC} Supply current	No load, $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$		11	20	mA

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 5$ V $\pm$ 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	D _{OUT} at R _L = 3 k Ω to GND, D _{IN} = GND	5	9		V
V _{OL} Low-level output voltage	D _{OUT} at R _L = 3 k Ω to GND, D _{IN} = V _{CC}	-5	-9		V
I _{IH} High-level input current	V _I = V _{CC}		15	200	μ A
I _{IL} Low-level input current	V _I at 0 V		-15	-200	μ A
I _{OS} [‡] Short-circuit output current	V _{CC} = 5.5 V, V _O = 0 V		± 10	± 60	mA
r _O Output resistance	V _{CC} , V ₊ , and V ₋ = 0 V, V _O = ± 2 V	300			Ω

[†] All typical values are at V_{CC} = 5 V, and T_A = 25°C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Maximum data rate	C _L = 50 to 1000 pF, R _L = 3 k Ω to 7 k Ω , One D _{OUT} switching, See Figure 1	120			kbit/s
t _{PLH} (D) Propagation delay time, low- to high-level output	C _L = 2500 pF, R _L = 3 k Ω , all drivers loaded, See Figure 1		2		μ s
t _{PHL} (D) Propagation delay time, high- to low-level output	C _L = 2500 pF, R _L = 3 k Ω , all drivers loaded, See Figure 1		2		μ s
t _{sk} (p) Pulse skew [§]	C _L = 150 pF to 2500 pF, R _L = 3 k Ω to 7 k Ω , See Figure 2		300		ns
SR(tr) Slew rate, transition region (see Figure 1)	C _L = 50 pF to 1000 pF, R _L = 3 k Ω to 7 k Ω , V _{CC} = 5 V	3	6	30	V/ μ s

[†] All typical values are at V_{CC} = 5 V, and T_A = 25°C.

[§] Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

ESD protection

PIN	TEST CONDITIONS	TYP	UNIT
D _{OUT} , R _{IN}	Human-Body Model	± 15	kV

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RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH} High-level output voltage	$I_{OH} = -1$ mA	3.5	$V_{CC} - 0.4$ V		V
V_{OL} Low-level output voltage	$I_{OL} = 1.6$ mA			0.4	V
V_{IT+} Positive-going input threshold voltage	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$		1.7	2.4	V
V_{IT-} Negative-going input threshold voltage	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$	0.8	1.2		V
V_{hys} Input hysteresis ($V_{IT+} - V_{IT-}$)		0.2	0.5	1	V
r_i Input resistance	$V_I = \pm 3$ V to ± 25 V	3	5	7	k Ω

† All typical values are at $V_{CC} = 5$ V, and $T_A = 25^\circ\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μF at $V_{CC} = 5$ V $\pm$ 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 3)

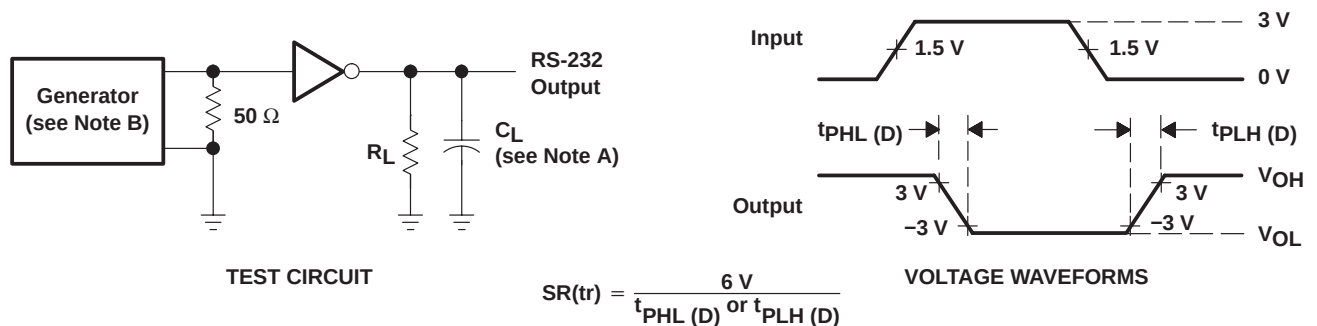
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	$C_L = 150$ pF		0.5	10	μs
t_{PHL} Propagation delay time, high- to low-level output			0.5	10	μs
$t_{sk(p)}$ Pulse skew‡			300		ns

† All typical values are at $V_{CC} = 5$ V, and $T_A = 25^\circ\text{C}$.

‡ Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μF , at $V_{CC} = 5$ V $\pm$ 0.5 V.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 1. Driver Slew Rate

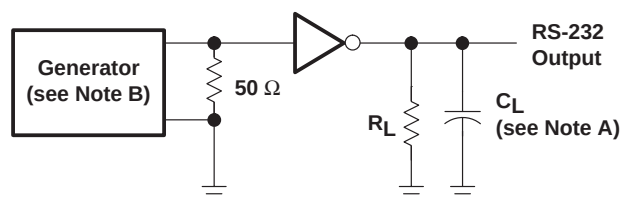
MAX207

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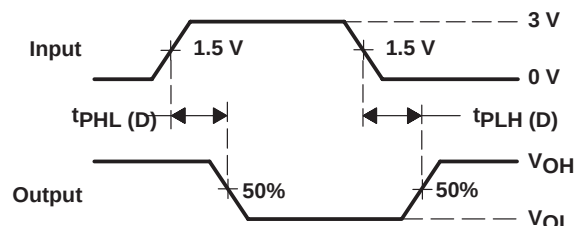
WITH ± 15 -kV ESD PROTECTION

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PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

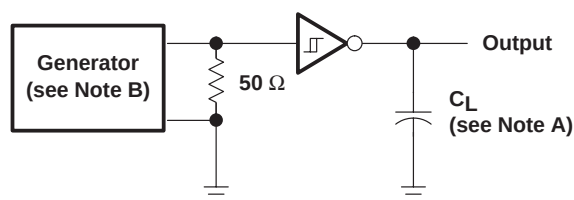


VOLTAGE WAVEFORMS

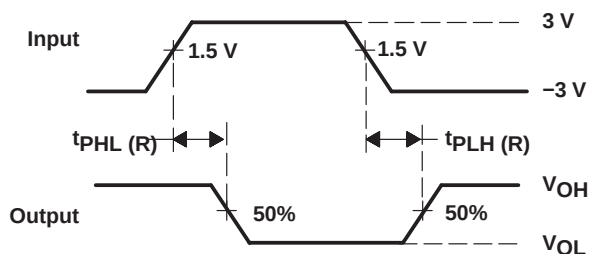
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 2. Driver Pulse Skew



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 3. Receiver Propagation Delay Times

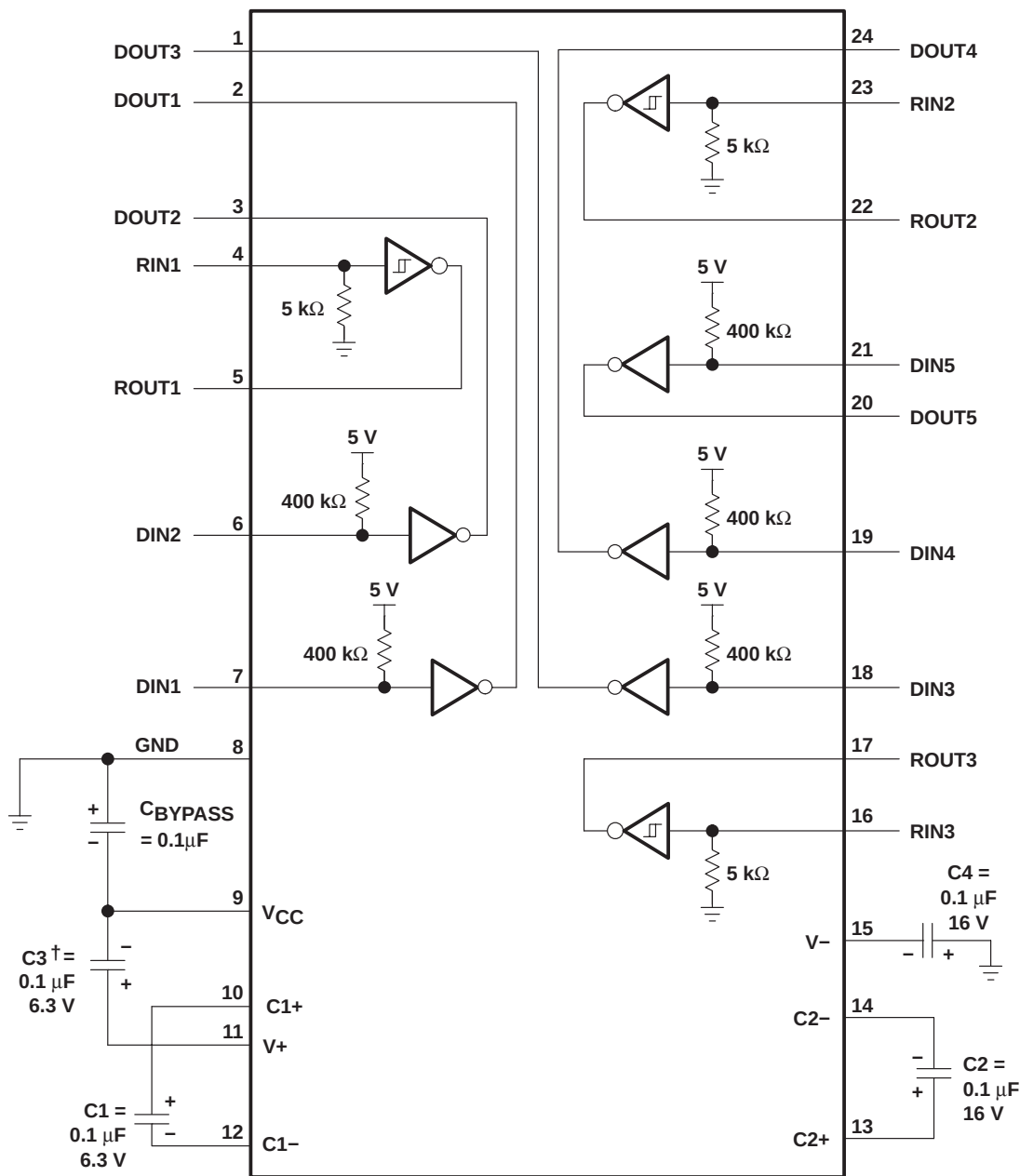
MAX207

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APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

Figure 4. Typical Operating Circuit and Capacitor Values

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APPLICATION INFORMATION

capacitor selection

The capacitor type used for C1–C4 is not critical for proper operation. The MAX207 requires 0.1- μ F capacitors, although capacitors up to 10 μ F can be used without harm. Ceramic dielectrics are suggested for the 0.1- μ F capacitors. When using the minimum recommended capacitor values, make sure the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (e.g., 2 $\times$) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V–.

Use larger capacitors (up to 10 μ F) to reduce the output impedance at V+ and V–.

Bypass V_{CC} to ground with at least 0.1 μ F. In applications sensitive to power-supply noise generated by the charge pumps, decouple V_{CC} to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1–C4).

ESD protection

TI MAX207 devices have standard ESD protection structures incorporated on the pins to protect against electrostatic discharges encountered during assembly and handling. In addition, the RS232 bus pins (driver outputs and receiver inputs) of these devices have an extra level of ESD protection. Advanced ESD structures were designed to successfully protect these bus pins against ESD discharge of ± 15 -kV when powered down.

ESD test conditions

ESD testing is stringently performed by TI, based on various conditions and procedures. Please contact TI for a reliability report that documents test setup, methodology, and results.

Human-Body Model

The Human-Body Model (HBM) of ESD testing is shown in Figure 5, while Figure 6 shows the current waveform that is generated during a discharge into a low impedance. The model consists of a 100-pF capacitor, charged to the ESD voltage of concern, and subsequently discharged into the device under test (DUT) through a 1.5-k Ω resistor.

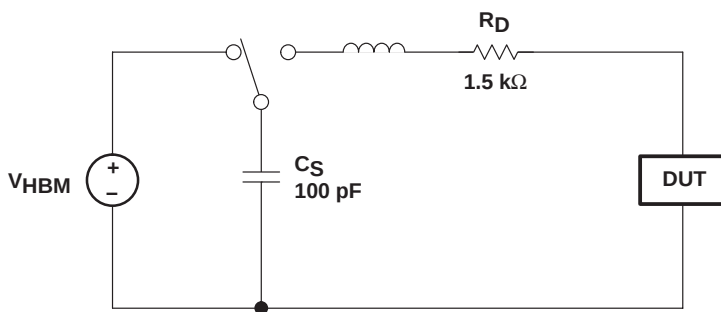


Figure 5. HBM ESD Test Circuit

APPLICATION INFORMATION

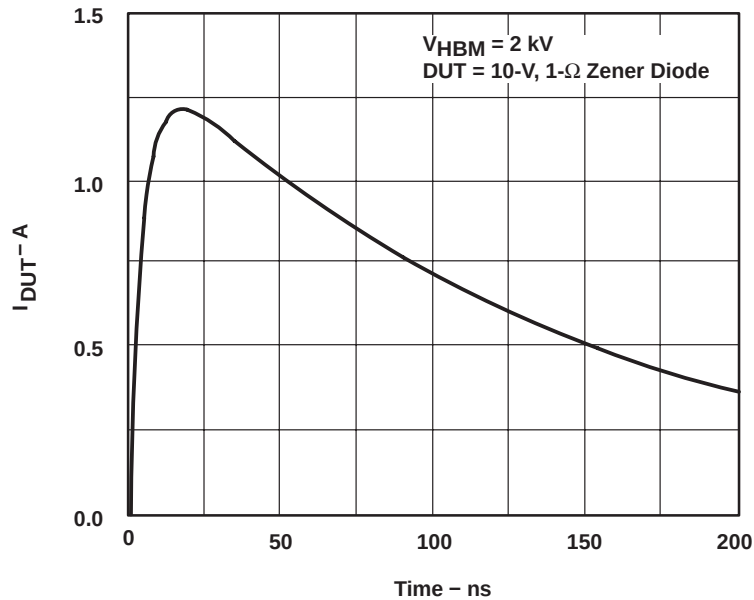


Figure 6. Typical HBM Current Waveform

Machine Model

The Machine Model (MM) ESD test applies to all pins using a 200-pF capacitor with no discharge resistance. The purpose of the MM test is to simulate possible ESD conditions that can occur during the handling and assembly processes of manufacturing. In this case, ESD protection is required for all pins, not just RS-232 pins. However, after PC board assembly, the MM test no longer is as pertinent to the RS-232 pins.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX207CDB	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDBE4	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDBG4	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207CDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDB	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDBE4	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDBG4	ACTIVE	SSOP	DB	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX207IDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

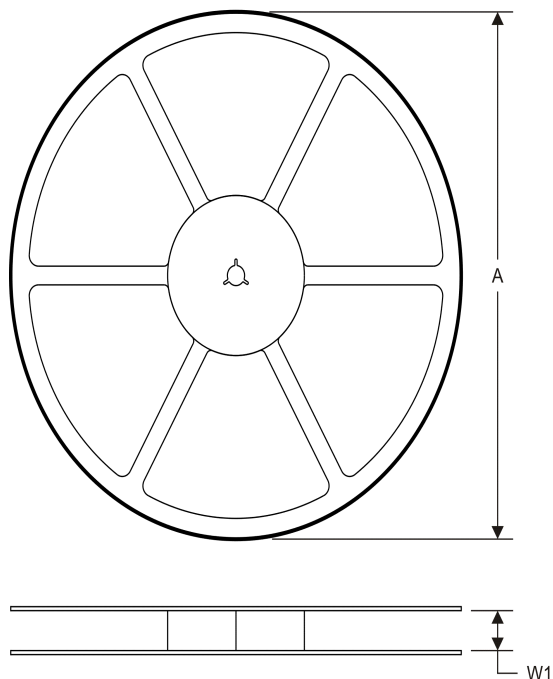
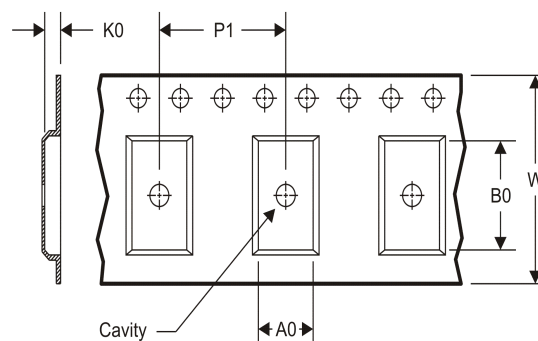
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


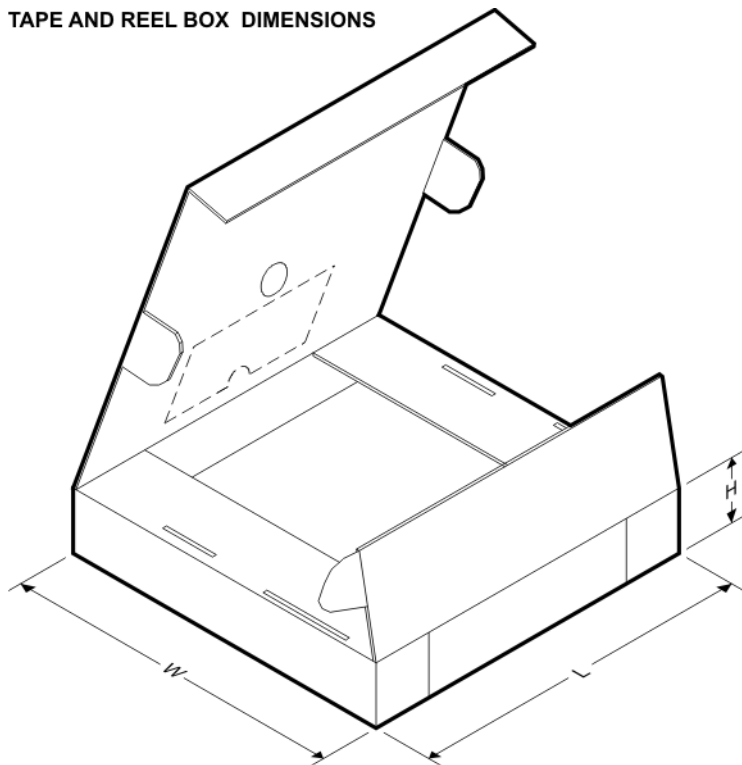
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX207CDBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
MAX207CDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
MAX207IDBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
MAX207IDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

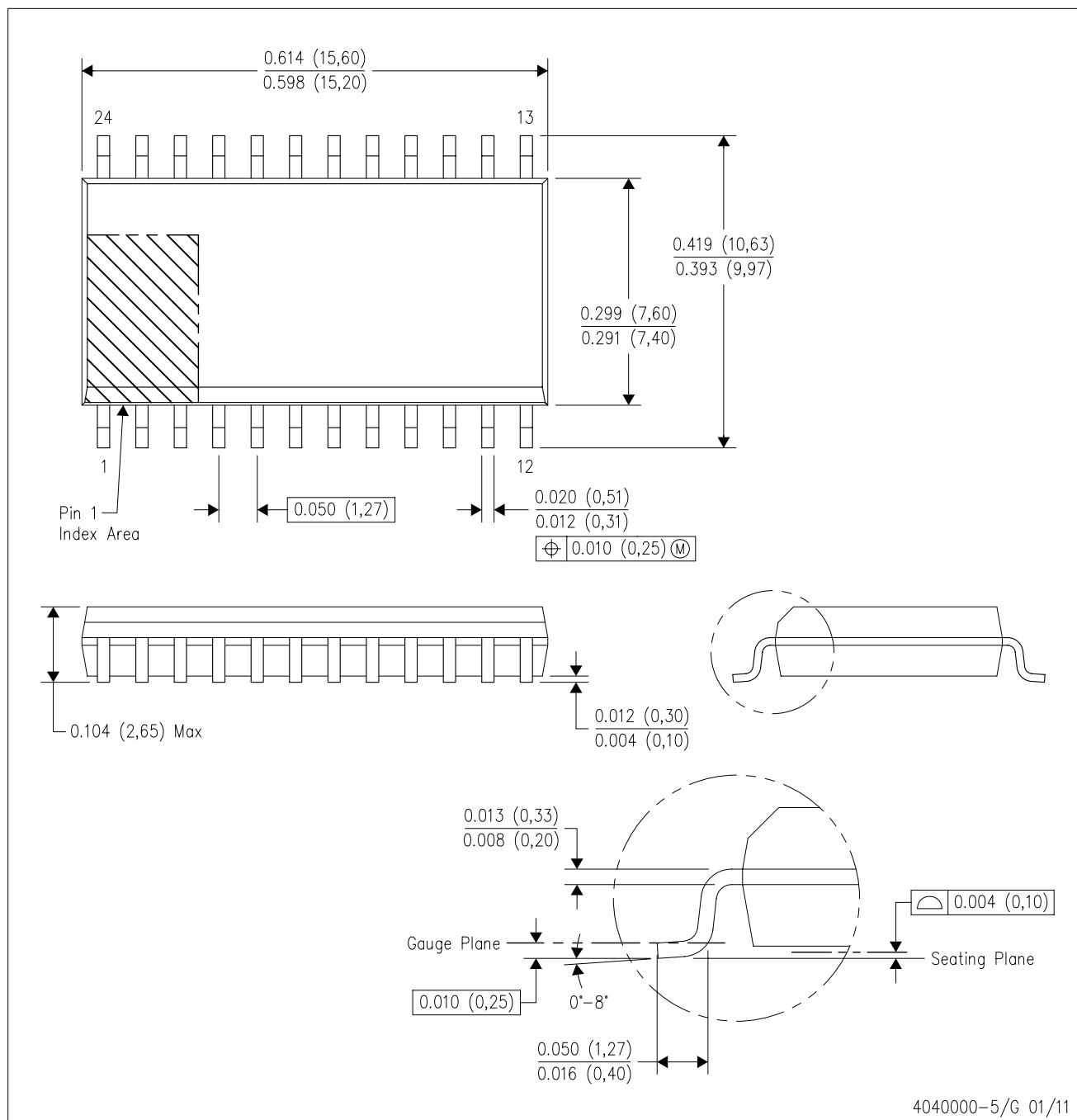


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX207CDBR	SSOP	DB	24	2000	367.0	367.0	38.0
MAX207CDWR	SOIC	DW	24	2000	367.0	367.0	45.0
MAX207IDBR	SSOP	DB	24	2000	367.0	367.0	38.0
MAX207IDWR	SOIC	DW	24	2000	367.0	367.0	45.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

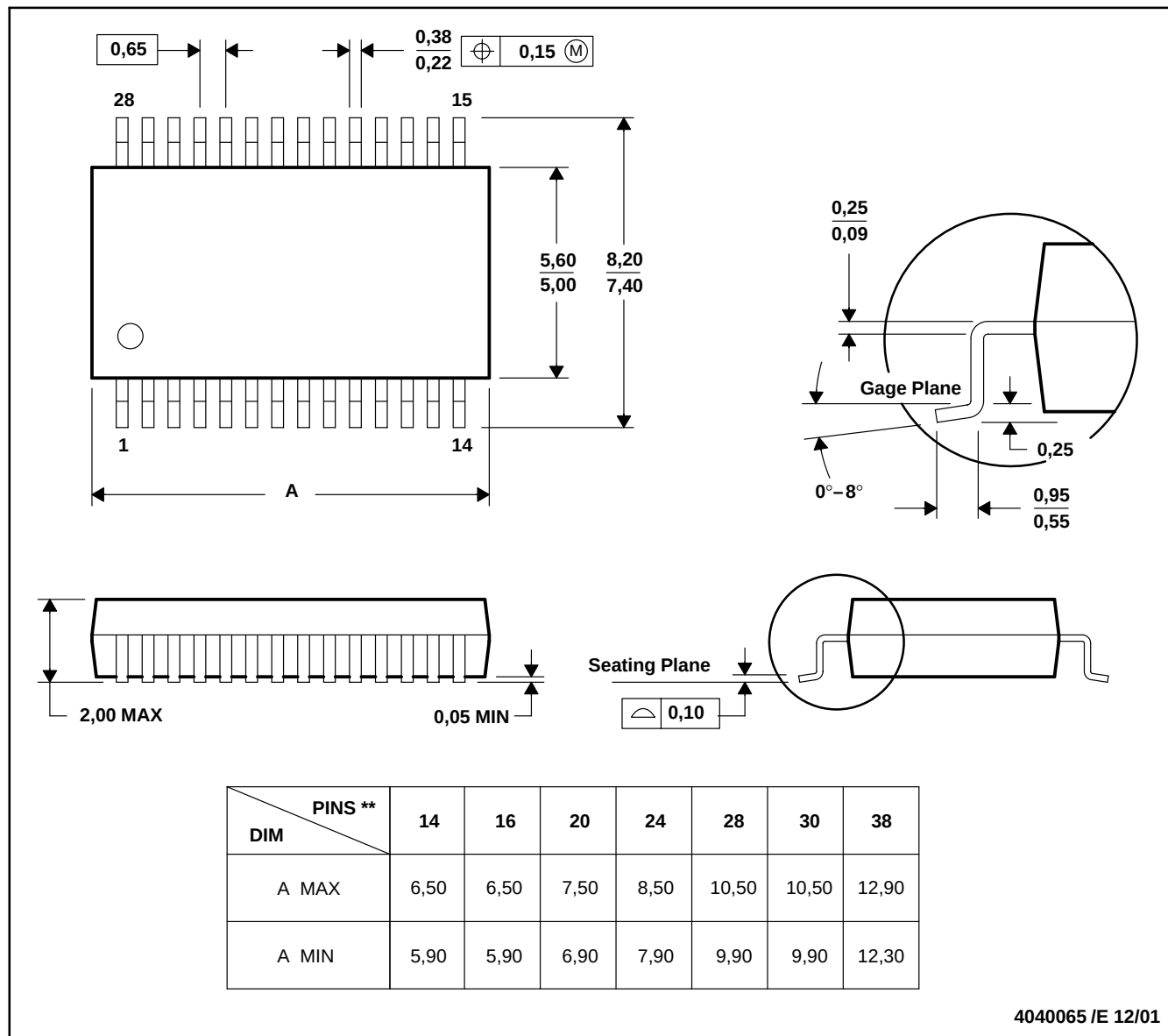


- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AD.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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